

Description

The DGD2304 is a high voltage / high speed gate driver capable of driving N-channel MOSFETs and IGBTs in a half bridge configuration. High voltage processing techniques enable the DGD2304's high side to switch to 600V in a bootstrap operation.

The DGD2304 logic inputs are compatible with standard TTL and CMOS levels (down to 3.3V) to interface easily with controlling devices. The driver outputs feature high pulse current buffers designed for minimum driver cross conduction. An internal deadtime of 100ns protects high-voltage MOSFETs from shoot-through.

The DGD2304 is offered in the SO-8 package and operates over an extended -40°C to +125°C temperature range.

Applications

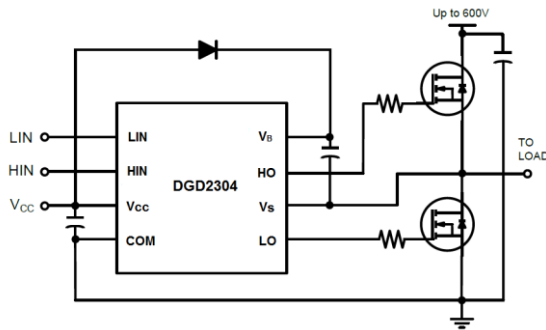
- DC-DC Converters
- DC-AC Inverters
- AC-DC Power Supplies
- Motor Controls
- Class D Power Amplifiers

Features

- Floating High-Side Driver in Bootstrap Operation to 600V
 - Drives Two N-channel MOSFETs or IGBTs in a Half Bridge Configuration
 - 290mA Source/600mA Sink Output Current Capability
 - Outputs Tolerant to Negative Transients
 - Internal Logic and Dead Time (100ns) to Protect MOSFETs
 - Logic Input (HIN and LIN) 3.3V Capability
 - Schmitt Triggered Logic Inputs with Internal Pull Down
 - Undervoltage Lockout for High and Low Side Drivers
 - Extended Temperature Range: -40°C to +125°C
 - **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
 - **Halogen and Antimony Free. "Green" Device (Note 3)**
 - **For automotive applications requiring specific change control (i.e. parts qualified to AEC-Q100/101/200, PPAP capable, and manufactured in IATF 16949 certified facilities), please [contact us](#) or your local Diodes representative.**
- <https://www.diodes.com/quality/product-definitions/>

Mechanical Data

- Case: SO-8
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 3 per J-STD-020
- Terminals: Finish – Matte Tin Plated Leads, Solderable per MIL-STD-202, Method 208 (E3)
- Weight: 0.075 grams (Approximate)



Typical Configuration



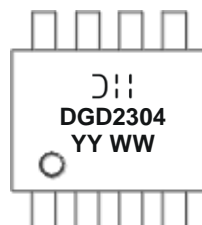
SO-8
Top View

Ordering Information (Note 4)

| Part Number | Marking | Reel Size (inches) | Tape Width (mm) | Quantity per Reel |
|--------------|---------|--------------------|-----------------|-------------------|
| DGD2304S8-13 | DGD2304 | 13 | 12 | 2,500 |

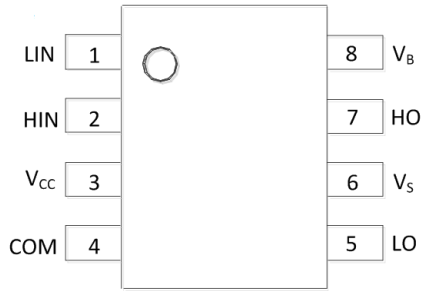
- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
 2. See <https://www.diodes.com/quality/lead-free/> for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <https://www.diodes.com/design/support/packaging/diodes-packaging/>.

Marking Information



DII = Manufacturer's Marking
 DGD2304 = Product Type Marking Code
 YY = Year (ex: 20 = 2020)
 WW or WW- = Week (01 to 53)

Pin Diagrams

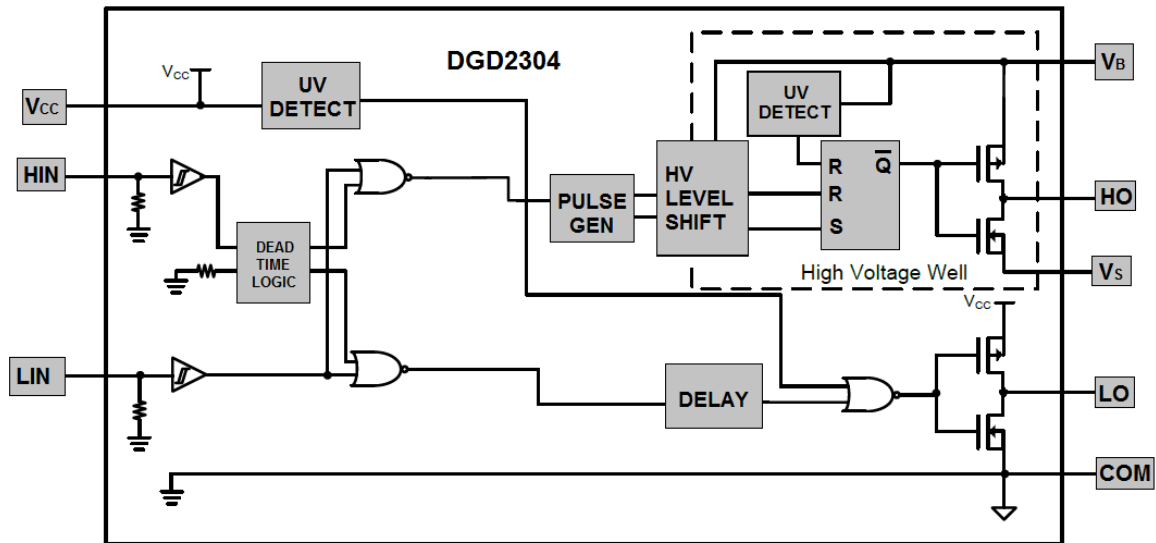


Top View: SO-8

Pin Descriptions

| Pin Number | Pin Name | Function |
|------------|-----------------|---|
| 1 | LIN | Logic input for Low-Side Gate Driver Output in Phase with LO |
| 2 | HIN | Logic Input for High-Side Gate Driver Output in Phase with HO |
| 3 | V _{cc} | Low Side and Logic Fixed Supply |
| 4 | COM | Low-Side and Logic Return |
| 5 | LO | Low-Side Gate Drive Output |
| 6 | V _s | High-Side Floating Supply Return |
| 7 | HO | High-Side Gate Drive Output |
| 8 | V _B | High-Side Floating Supply |

Functional Block Diagram



Absolute Maximum Ratings (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|--|----------------------|--|------|
| High-Side Floating Supply Voltage | V _B | -0.3 to +624 | V |
| High-Side Floating Supply Offset Voltage | V _S | V _B -24 to V _B +0.3 | V |
| High-Side Floating Output Voltage | V _{HO} | V _S -0.3 to V _B +0.3 | V |
| Offset Supply Voltage Transient | dV _S / dt | 50 | V/ns |
| Low-Side and Logic Fixed Supply Voltage | V _{CC} | -0.3 to +24 | V |
| Low-Side Output Voltage | V _{LO} | -0.3 to V _{CC} +0.3 | V |
| Logic Input Voltage (HIN and LIN) | V _{IN} | V _{SS} -0.3 to V _{CC} +0.3 | V |

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

| Characteristic | Symbol | Value | Unit |
|---|------------------|-------------|------|
| Power Dissipation Linear Derating Factor (Note 5) | P _D | 1.25 | W |
| Thermal Resistance, Junction to Ambient (Note 5) | R _{θJA} | 55 | °C/W |
| Operating Temperature | T _J | +150 | °C |
| Lead Temperature (Soldering, 10s) | T _L | +300 | |
| Storage Temperature Range | T _{STG} | -55 to +150 | |

Note: 5. When mounted on a standard JEDEC 2-layer FR-4 board.

Recommended Operating Conditions

| Parameter | Symbol | Min | Max | Unit |
|--|-----------------|---------------------|---------------------|------|
| High-Side Floating Supply Absolute Voltage | V _B | V _S + 10 | V _S + 20 | V |
| High-Side Floating Supply Offset Voltage | V _S | (Note 6) | 600 | V |
| High-Side Floating Output Voltage | V _{HO} | V _S | V _B | V |
| Low-Side and Logic Fixed Supply Voltage | V _{CC} | 10 | 20 | V |
| Low-Side Output Voltage | V _{LO} | 0 | V _{CC} | V |
| Logic Input Voltage | V _{IN} | 0 | 5 | V |
| Ambient Temperature | T _A | -40 | +125 | °C |

Note: 6. Logic operation for V_S of -5V to +600V. Logic state held for V_S of -5V to -V_{BS}.

DC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, @ T_A = +25°C, unless otherwise specified.) (Note 7)

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|--|-------------|-----|------|-----|---------|----------------------------------|
| Logic "1" Input Voltage | V_{IH} | 2.3 | — | — | V | $V_{CC} = 10V$ to 20V |
| Logic "0" Input Voltage | V_{IL} | — | — | 0.7 | V | $V_{CC} = 10V$ to 20V |
| High Level Output Voltage, $V_{BIAS} - V_O$ | V_{OH} | — | 0.05 | 0.2 | V | $I_O = 2mA$ |
| Low Level Output Voltage, V_O | V_{OL} | — | 0.02 | 0.1 | V | $I_O = 2mA$ |
| Offset Supply Leakage Current | I_{LK} | — | — | 50 | μA | $V_B = V_S = 600V$ |
| Quiescent V_{BS} Supply Current | I_{BSQ} | 20 | 60 | 150 | μA | $V_{IN} = 0V$ or 5V |
| Quiescent V_{CC} Supply Current | I_{CCQ} | 50 | 260 | 400 | μA | $V_{IN} = 0V$ or 5V |
| Logic "1" Input Bias Current | I_{IN+} | — | 5.0 | 40 | μA | $V_{IN} = 5V$ |
| Logic "0" Input Bias Current | I_{IN-} | — | 1.0 | 5.0 | μA | $V_{IN} = 0V$ |
| V_{BS} Supply Under-Voltage Positive Going Threshold | V_{BSUV+} | 7.7 | 8.7 | 9.7 | V | — |
| V_{BS} Supply Under-Voltage Negative Going Threshold | V_{BSUV-} | 7.0 | 8.0 | 9.0 | V | — |
| V_{CC} Supply Under-Voltage Positive Going Threshold | V_{CCUV+} | 7.7 | 8.7 | 9.7 | V | — |
| V_{CC} Supply Under-Voltage Negative Going Threshold | V_{CCUV-} | 7.0 | 8.0 | 9.0 | V | — |
| Output High Short Circuit Pulsed Current | I_{O+} | 60 | 290 | — | mA | $V_O = 0V$, $P_W \leq 10\mu s$ |
| Output Low Short Circuit Pulsed Current | I_{O-} | 130 | 600 | — | mA | $V_O = 15V$, $P_W \leq 10\mu s$ |

Note: 7. The V_{IN} and I_{IN} parameters are referenced to COM and are applicable to the two logic pins: HIN and LIN. The V_O and I_O parameters are referenced to COM and are applicable to the respective output pins: HO and LO.

AC Electrical Characteristics (V_{BIAS} (V_{CC} , V_{BS}) = 15V, $C_L = 1000pF$, @ T_A = +25°C, unless otherwise specified.)

| Parameter | Symbol | Min | Typ | Max | Unit | Conditions |
|--|------------|-----|-----|-----|------|--------------------|
| Turn-On Propagation Delay | t_{ON} | — | 95 | 210 | ns | $V_S = 0V$ |
| Turn-Off Propagation Delay | t_{OFF} | — | 100 | 210 | ns | $V_S = 0V$ or 600V |
| Delay Matching, HO and LO Turn-On / Turn-Off | t_{DMON} | — | — | 50 | ns | — |
| Turn-On Rise Time | t_r | — | 70 | 120 | ns | — |
| Turn-Off Fall Time | t_f | — | 35 | 60 | ns | — |
| Deadtime: $t_{DT LO-HO}$ and $t_{DT HO-LO}$ | t_{DT} | 80 | 100 | 190 | ns | — |

Timing Waveforms

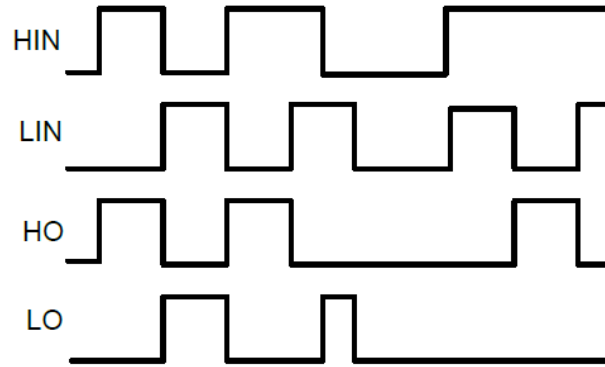


Figure 1. Input / Output Timing Diagram

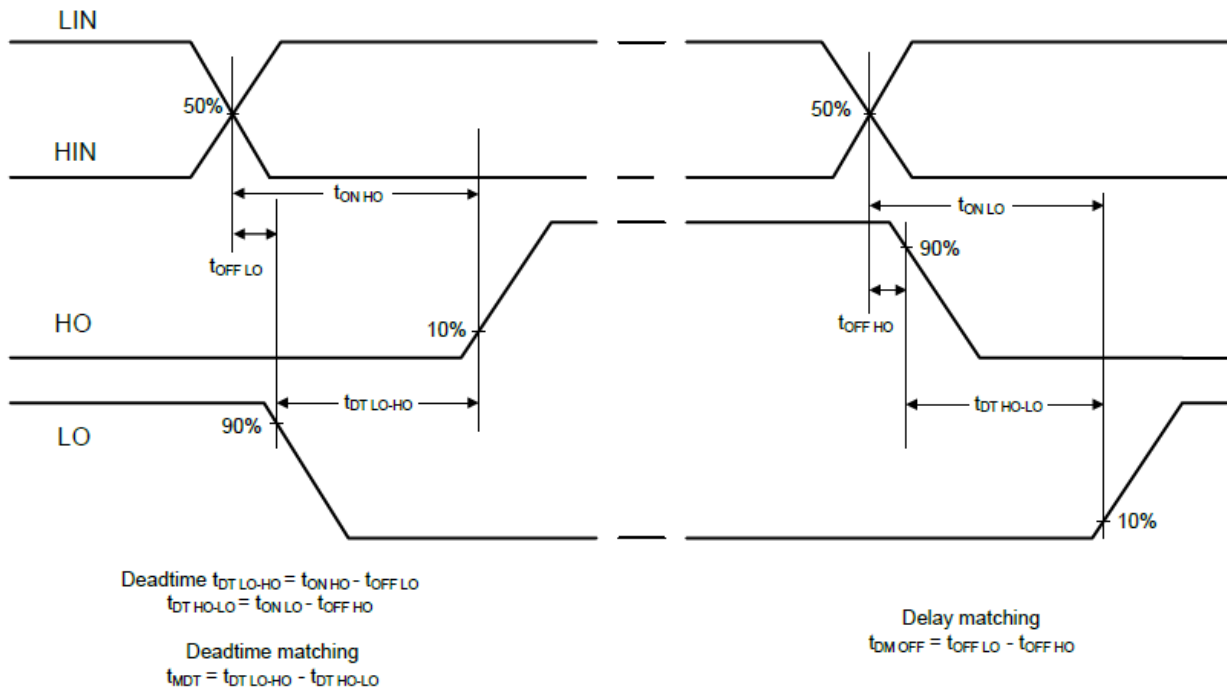


Figure 2. Switching Time Waveform Definition

Typical Performance Characteristics ($V_{CC} = 15V$, $@T_A = +25^\circ C$, unless otherwise specified.)

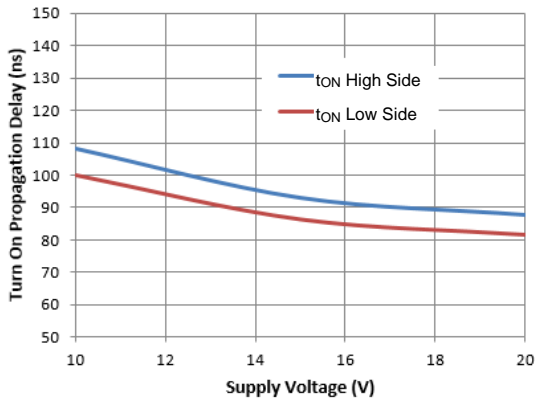


Figure 3. Turn-on Propagation Delay vs. Supply Voltage

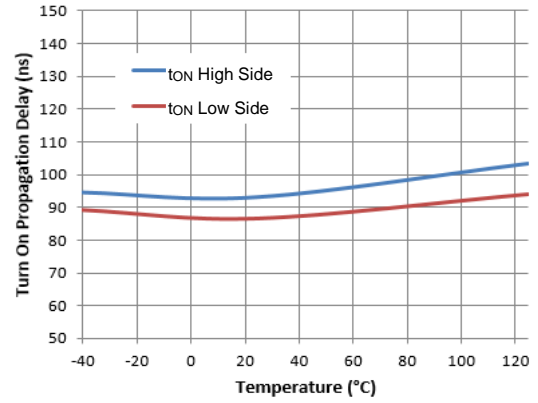


Figure 4. Turn-on Propagation Delay vs. Temperature

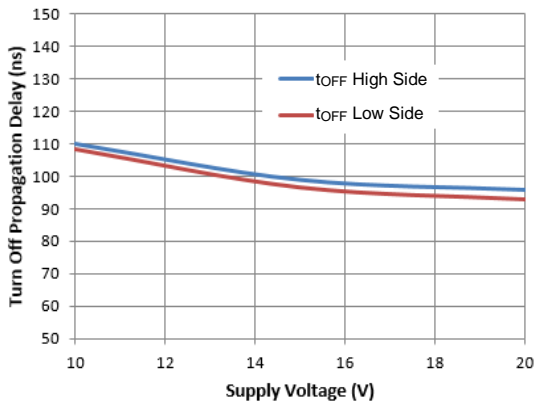


Figure 5. Turn-off Propagation Delay vs. Supply Voltage

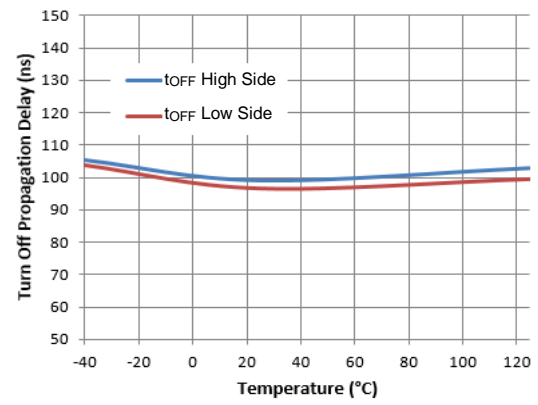


Figure 6. Turn-off Propagation Delay vs. Temperature

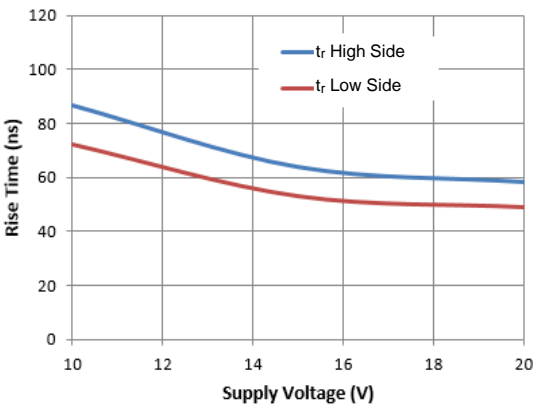


Figure 7. Rise Time vs. Supply Voltage

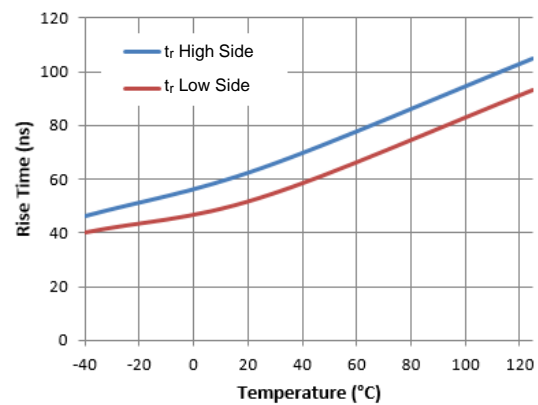


Figure 8. Rise Time vs. Temperature

Typical Performance Characteristics (continued)

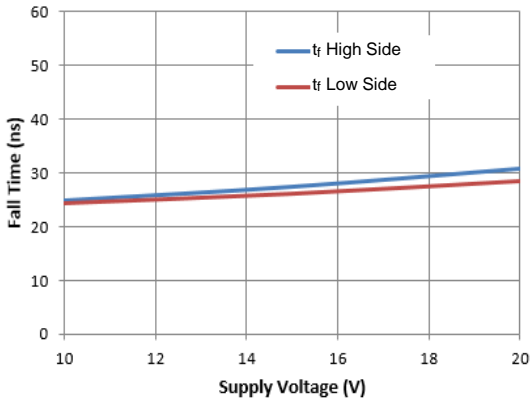


Figure 9. Fall Time vs. Supply Voltage

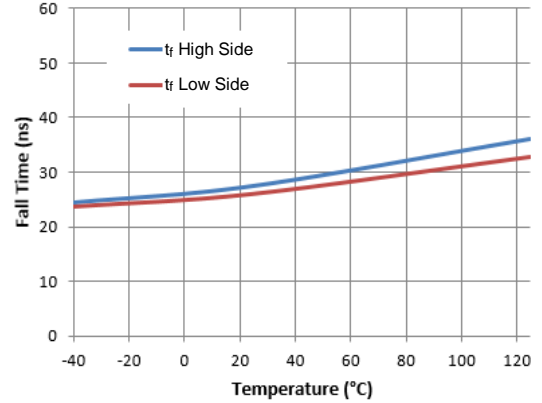


Figure 10. Fall Time vs. Temperature

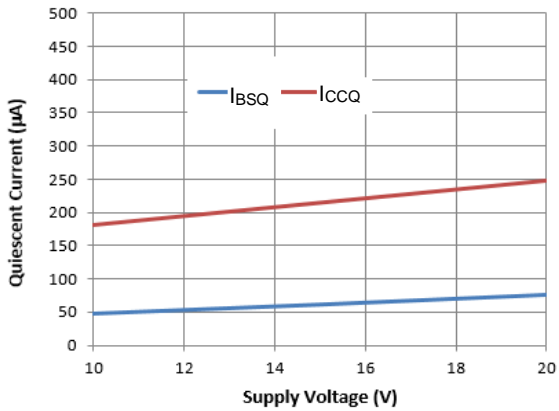


Figure 11. Quiescent Current vs. Supply Voltage

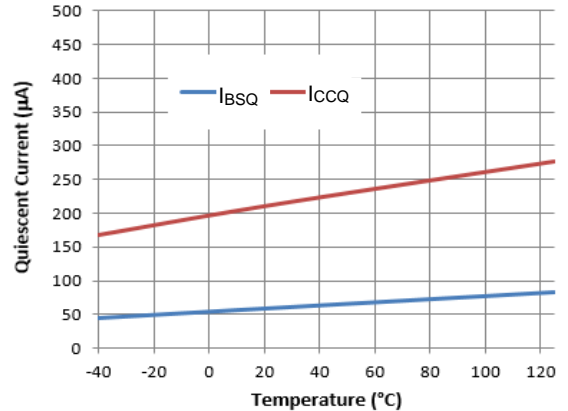


Figure 12. Quiescent Current vs. Temperature

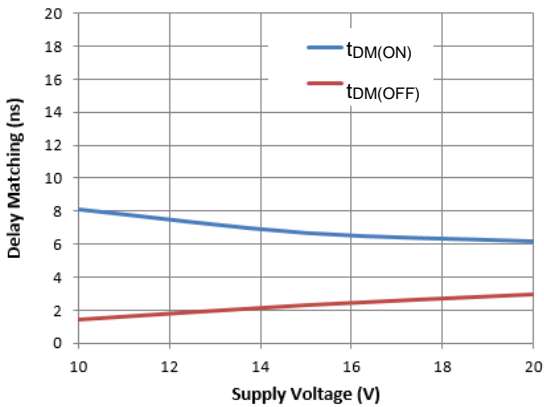


Figure 13. Delay Matching vs. Supply Voltage

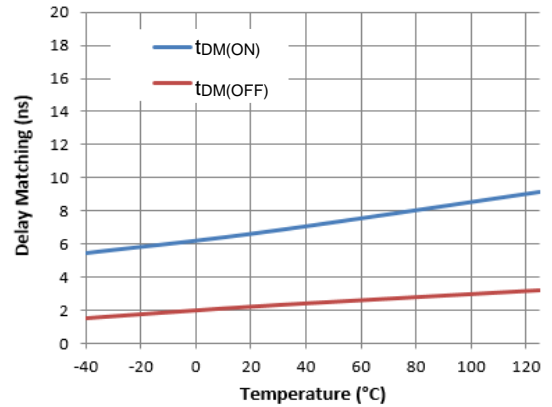


Figure 14. Delay Matching vs. Temperature

Typical Performance Characteristics (continued)

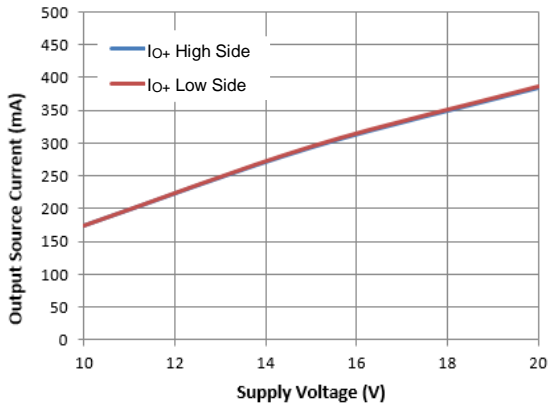


Figure 15. Output Source Current vs. Supply Voltage

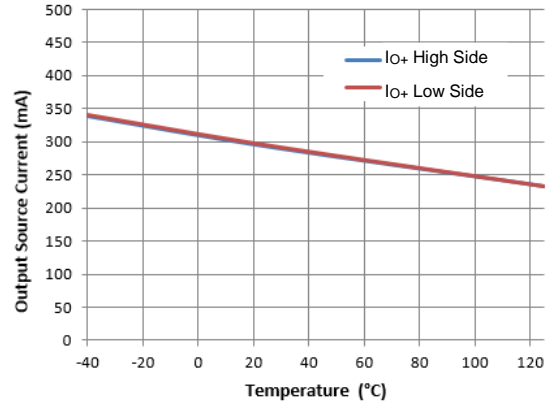


Figure 16. Output Source Current vs. Temperature

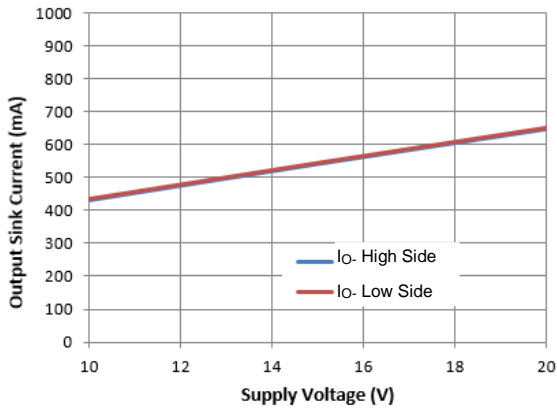


Figure 17. Output Sink Current vs. Supply Voltage

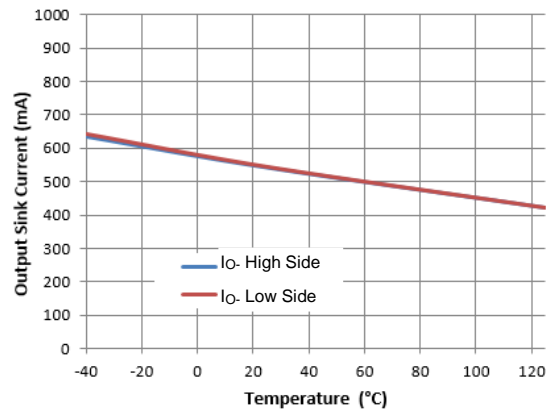


Figure 18. Output Sink Current vs. Temperature

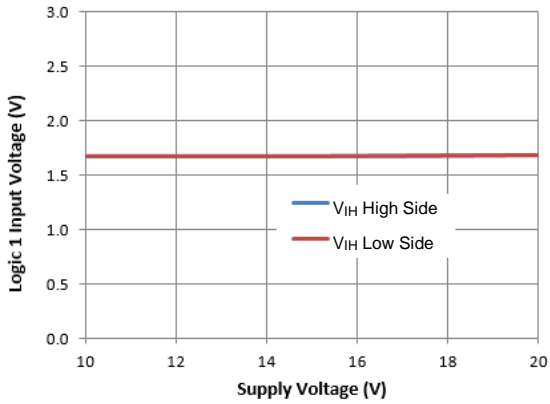


Figure 19. Logic 1 Input Voltage vs. Supply Voltage

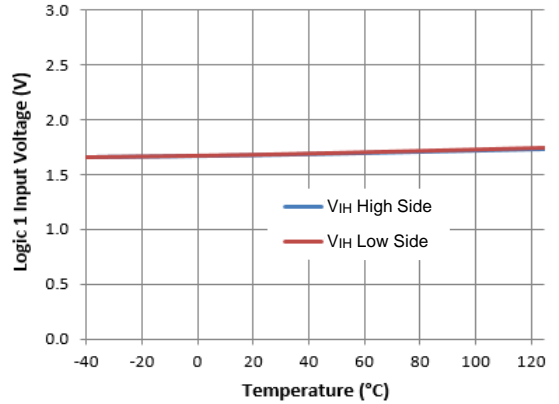


Figure 20. Logic 1 Input Voltage vs. Temperature

Typical Performance Characteristics (continued)

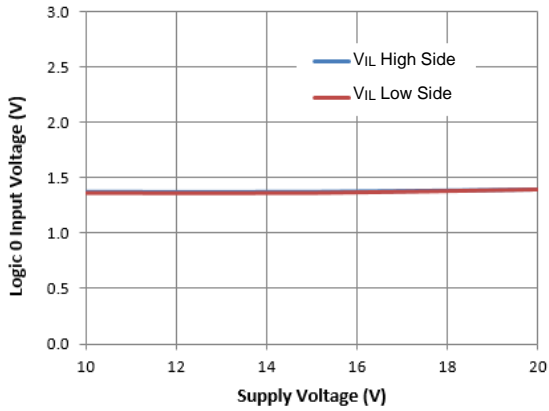


Figure 21. Logic 0 Input Voltage vs. Supply Voltage

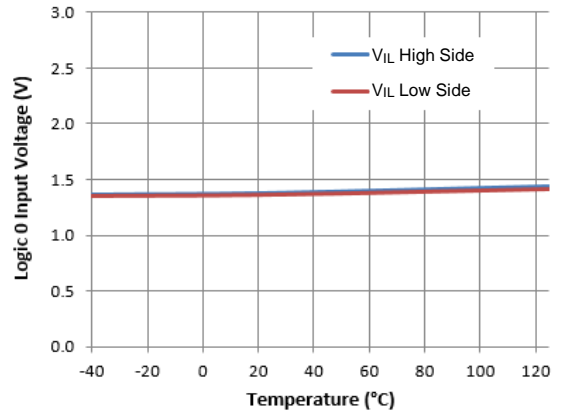


Figure 22. Logic 0 Input Voltage vs. Temperature

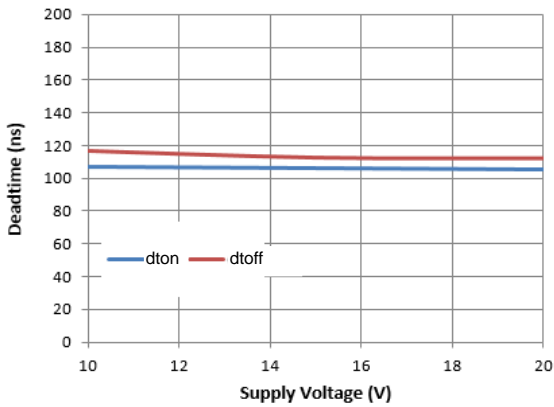


Figure 23. Deadtime vs. Supply Voltage

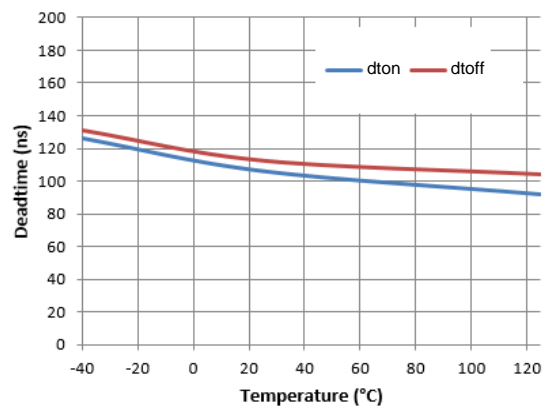


Figure 24. Deadtime vs. Temperature

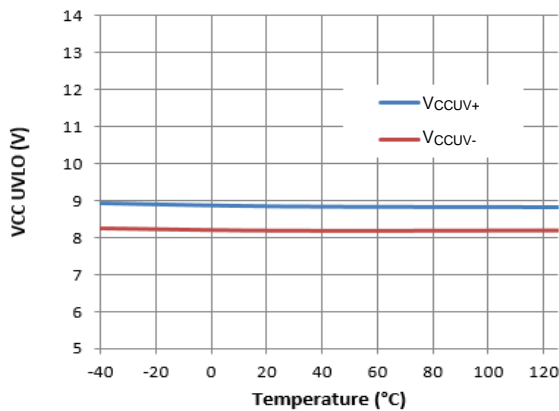


Figure 25. VCC UVLO vs. Temperature

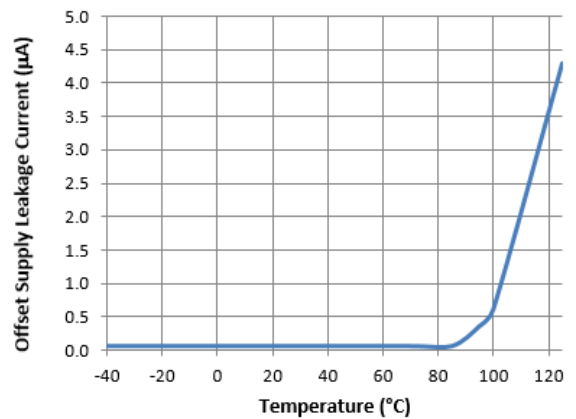
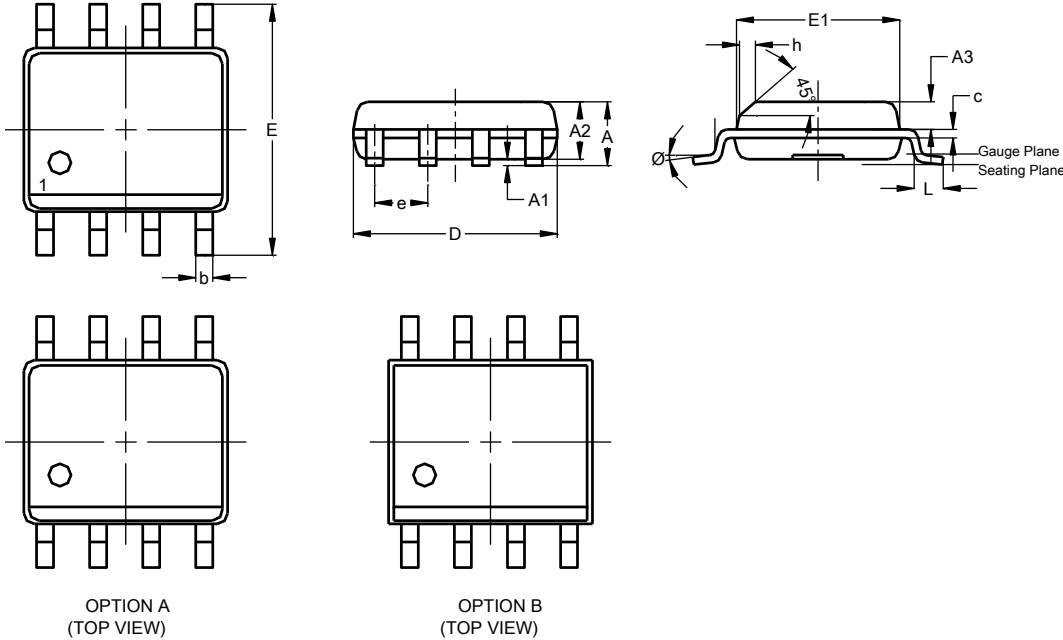


Figure 26. Offset Supply Leakage Current vs. Temperature

Package Outline Dimensions

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

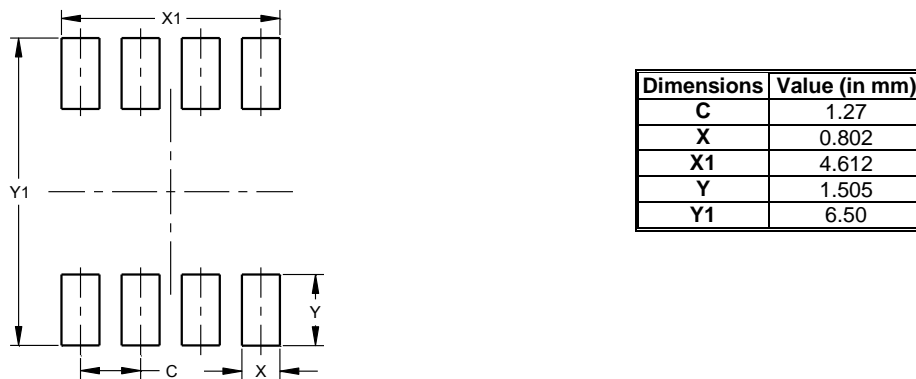
SO-8 (Standard)



Suggested Pad Layout

Please see <http://www.diodes.com/package-outlines.html> for the latest version.

SO-8 (Standard)



Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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